CRITERIA	Criteria 1: Policy		Criteria 2:	Criteria 3:	
Action Title	Appraisal ++ highly relevant + relevant		Appraisal ++ good fit [4] + fit [1, 2,3] 0 challenging fit[0] - bad fit [<0]	Appraisal ++ highly consistent + consistent 0 not consistent	Planning
Microelectronics and On-board Data S					
JTF-2018/20-2 ASICS for mixed signal processing [U11]	++	3	+	++ (from 2019)	2019
JTF-2018/20-3 - High Capacity FPGAs [U12]	++	2	+	++ (from 2020)	2020
JTF-2018/20-5 - Very high performance microprocessors [U20] (LEON)	++	3	+ (LEON)	++ (from 2020)	2020
JTF-2018/20-7 - ASICS: 65nm Deep Sub-Micron (DSM) [U22a]	++	2	+	++	2019
JTF-2018/20-8 - ASICS: 28nm Deep Sub-Micron (DSM) [U22b]	++	1	+	++	2018
JTF-2018/20-9 - Design and prototype of ultra- reprogrammable SoCs [N50]	++	2	+	++	2019
JTF-2018/20-11 - Design and Qualification of uController for Space application [N52]	++	4	++	+	2018
JTF-2018/20-12 - Design and prototype of nvRAM for SPACE with Serial interface ((quad)-SPI) [N53]	++	4	++	++	2019
Space System Control					
JTF-2018/20-14 - Fiber optic or photonics integrated technology Gyro based inertial measurement unit (IMU) [U6]	++	4	++	+	2020
Power JTF-2018/20-16 - Active discrete power					
components [U14]	++	2	+	++	2018
RF Payload System JTF-2018/20-17 - Power amplification:				(6 - 2020)	
Travelling Wave Tube (TWT) materials [U7]	++	3	+	++ (from 2020)	2020
EEE components					
JTF-2018/20-19- Passive components [U13]	++	3	+	++	2018
JTF-2018/20-22 – High Temperature Packaging [N49]	++	3	+	++	2018
Software					
JTF-2018/20-23 - SW tool: Automatic Generation of code [N64]	++	4	++	+	2020
Space Environment and Effects					
JTF-2018/20-24 - Spacecraft charging simulation tool [U8]	++	4	++	+	2020
Mechanisms					
JTF-2018/20-25 - Space qualification of low shock Non-Explosive Actuators (NEA) [U1]	++	2	+	++ (from 2019)	2019
Materials and Processes					
Optics and Optoelectronics					
JTF-2018/20-31 - Advanced Laser Crystals for High Power Space applications [N63]	++	4	++	++	2019
Propulsion					
JTF-2018/20-33 - Advanced materials and material technology for combustion chambers [U4]	++	1	+	++	2018
Structure and Thermal					

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